

HIGH-SPEED SILICON DIODES FOR SURFACE MOUNTING

These diodes are primarily designed for fast logic applications.

These SM diodes are leadless diodes in a hermetically sealed SOD80C envelope with tin-plated metal discs at each end. They are suitable for "automatic placement" and as such it can withstand immersion soldering.

The diodes are delivered in "super 8" tape.

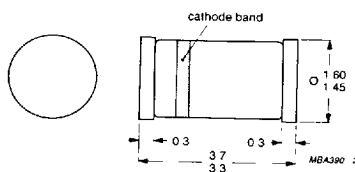
QUICK REFERENCE DATA

Continuous reverse voltage	V_R	max.	75 V
Repetitive peak reverse voltage	V_{RRM}	max.	75 V
Repetitive peak forward current	I_{FRM}	max.	450 mA
Forward voltage			
PMLL4148: $I_F = 10$ mA	V_F	<	1 V
PMLL4446: $I_F = 20$ mA			
PMLL4448: $I_F = 100$ mA			
Reverse recovery time when switched from $I_F = 10$ mA to $I_R = 60$ mA; $R_L = 100 \Omega$; measured at $I_R = 1$ mA	t_{rr}	<	4 ns

MECHANICAL DATA

Dimensions in mm

Fig. 1 SOD80C.



Cathode indicated by black band.

RATINGS

Limiting values in accordance with the Absolute Maximum System (IEC 134)

Continuous reverse voltage	V_R	max.	75 V
Repetitive peak reverse voltage	V_{RRM}	max.	75 V
Average rectified forward current	$I_{F(AV)}$	max.	150 mA
Forward current (d.c.)	I_F	max.	200 mA
Repetitive peak forward current	I_{FRM}	max.	450 mA
Non-repetitive peak forward current			
$t = 1 \mu s$	I_{FSM}	max.	2000 mA
$t = 1 s$	I_{FSM}	max.	500 mA
Total power dissipation up to $T_{amb} = 25^\circ C$	P_{tot}	max.	500 mW
Derating factor			2,85 mW/K
Storage temperature	T_{stg}		-65 to + 200 $^\circ C$
Junction temperature	T_j	max.	200 $^\circ C$

CHARACTERISTICS

$T_j = 25^\circ C$ unless otherwise specified

Forward voltages

PMLL4148: $I_F = 10 \text{ mA}$	
PMLL4446: $I_F = 20 \text{ mA}$	
PMLL4448: $I_F = 100 \text{ mA}$	
PMLL4448: $I_F = 5 \text{ mA}$	

V_F	<	1 V
V_F		0,62 to 0,72 V

Reverse avalanche breakdown voltage

$I_R = 100 \mu A$
$I_R = 5 \mu A$

$V_{(BR)R}$	>	100 V
$V_{(BR)R}$	>	75 V

Reverse currents

$V_R = 20 \text{ V}$
$V_R = 20 \text{ V}; T_j = 100^\circ C$
$V_R = 20 \text{ V}; T_j = 150^\circ C$

PMLL4448

I_R	<	25 nA
I_R	<	3 μA
I_R	<	50 μA

Diode capacitance

$V_R = 0; f = 1 \text{ MHz}$

C_d	<	4 pF
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Forward recovery voltage when switched

to $I_F = 50 \text{ mA}; t_r = 20 \text{ ns}$

V_{fr}	<	2,5 V
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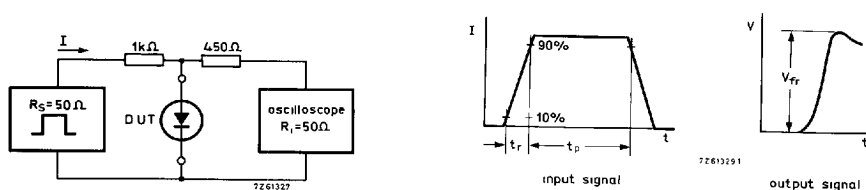


Fig. 2 Forward recovery voltage test circuit and waveforms.

Input signal: Rise time of the forward pulse $t_r = 20 \text{ ns}$
Forward current pulse duration $t_p = 120 \text{ ns}$
Duty factor $\delta = 0,01$

Oscilloscope: Rise time $t_r = 0,35 \text{ ns}$

Circuit capacitance $C \leq 1 \text{ pF}$ ($C = \text{oscilloscope input capacitance} + \text{parasitic capacitance}$)

Reverse recovery time when switched from
 $I_F = 10 \text{ mA}$ to $I_R = 60 \text{ mA}$; $R_L = 100 \Omega$;
measured at $I_R = 1 \text{ mA}$

$$t_{rr} < 4 \text{ ns}$$

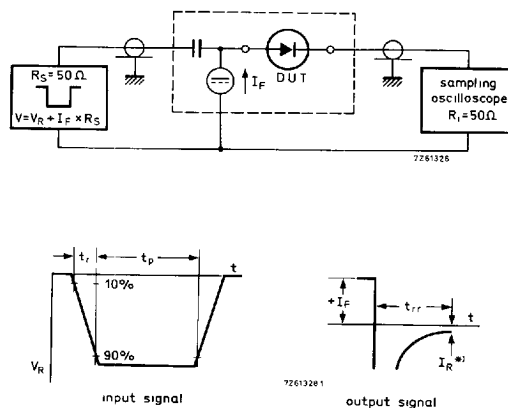


Fig. 3 Reverse recovery time test circuit and waveforms.

Input signal: Rise time of the reverse pulse $t_r = 0,6 \text{ ns}$
Reverse pulse duration $t_p = 100 \text{ ns}$
Duty factor $\delta = 0,05$

* $I_R = 1 \text{ mA}$

Oscilloscope: Rise time $t_r = 0,35 \text{ ns}$

Circuit capacitance $C \leq 1 \text{ pF}$ ($C = \text{oscilloscope input capacitance} + \text{parasitic capacitance}$)